

# **RKV650KL**

# Variable Capacitance Diode

REJ03G1286-0100 Rev.1.00 Oct 27, 2005

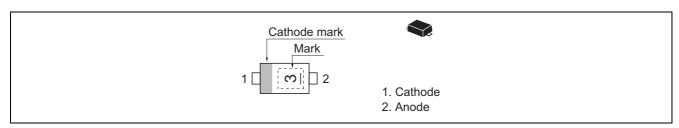
#### **Features**

- Most suitable for terrestrial digital TV broadcasts capable Mobile phones.
- High capacitance ratio. (n = 3.25 min)
- Low series resistance. (rs =  $0.75 \Omega \text{ max}$ )
- Extremely small Flat Lead Package (EFP) is suitable for surface mount design.

### **Ordering Information**

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
RKV650KL	3	EFP	PXSF0002ZA-A (EFP)

## **Pin Arrangement**



# **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit
Reverse voltage	$V_R$	15	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

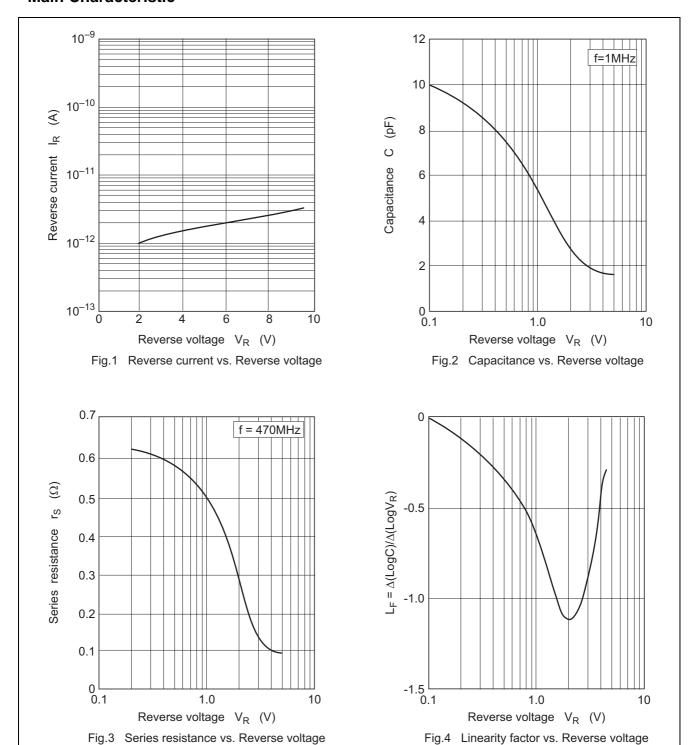
#### **Electrical Characteristics**

 $(Ta = 25^{\circ}C)$ 

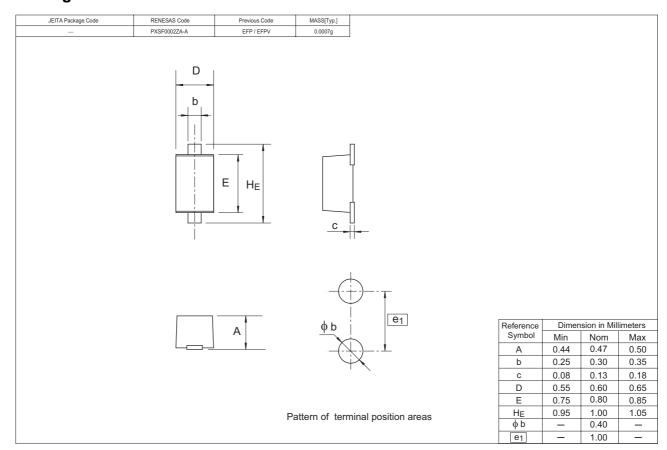
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I <sub>R1</sub>	_	_	10	nA	V <sub>R</sub> = 10 V
	I <sub>R2</sub>	_	_	100		$V_R = 10 \text{ V}, \text{ Ta} = 60^{\circ}\text{C}$
Capacitance	C <sub>0.5</sub>	7.20	_	7.80	pF	$V_R = 0.5 V, f = 1 MHz$
	C <sub>2.5</sub>	2.05	_	2.35		$V_R = 2.5 \text{ V}, f = 1 \text{ MHz}$
Capacitance ratio	n	3.25	_	3.70	_	C <sub>0.5</sub> / C <sub>2.5</sub>
Series resistance	r <sub>S</sub>			0.75	Ω	V <sub>R</sub> = 1 V, f = 470 MHz

Note: 1. For EFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

#### **Main Characteristic**



# **Package Dimensions**



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